



Product End of Life Notice

Notice: EOL1135

Product(s):

BDM1 Bi-Directional Module

IO1 Rear I/O for BDM1

BDM1 Chassis Redundancy Kits

BDM2 Bi-Directional Module

Issued: June 29, 2022

Casa Systems announces the end-of life for the BDM1 Module, BDM1 Chassis Redundancy Kit, IO1 Rear I/O, and BDM2 module (Broadcom Packet processor version as it is being replaced with a feature-matching Marvell processor version). Existing IO2 and SW-IO2 products remain applicable to new BDM2m platform. Customers with active support services contracts will continue to receive support from Casa Systems for the duration of the existing warranty and existing support services agreement, and customers may continue to purchase support services as shown in Table 1 of this Notice. Table 1 describes the end-of-life milestone dates for the affected product(s). Table 2 lists the product part numbers affected by this announcement and the recommended replacement part(s).

Table 1. End-of-Sale Milestones

Milestone	Milestone Definition
<i>End-of-Life Announcement:</i> June 29, 2022	The date of formal communication from Casa Systems to end of life the product(s).
<i>End-of-Sale:</i> Earlier of July 29, 2023, or When Inventory is Exhausted	The last date the product(s) may be purchased from Casa Systems.
<i>End of Software Maintenance:</i> June 29, 2030	The last date for software maintenance releases and/or bug fixes for the product(s).
<i>End of Hardware Warranty and Telephone Support:</i> June 29, 2030	The last date to receive hardware warranty and telephone support services for the product(s).

Table 2. Recommended Replacement Parts and Strategies

EOL Product Part Number	Recommended Replacement Product Part Number	Recommended Replacement Product Description
C40G-BDM-* C100G-BDM-*	C40G-BDM2M-* C100G-BDM2M-*	BDM2m Bi-Directional Module with Marvell Packet processor
C100G-BDM6+12-RD11-KIT C100G-BDM6+12-RD11-UPGR-KIT C40G-BDM6+12-RD3-KIT C40G-BDM6+12-RD3-UPGR-KIT	C100G-BDM6+12-RD11-KIT2 C100G-BDM6+12-RD11-UPGR-KIT2 C40G-BDM6+12-RD3-KIT2 C40G-BDM6+12-RD3-UPGR-KIT2	SW-IO2-based Redundancy Kits
C40G-BDM6+12-IO C100G-BDM6+12-IO	C40G-BDM6+12-IO2 C100G-BDM6+12-IO2	High-Split Capable IO boards (remain identical between BDM2 and BDM2m)
C40G-BDM2-* C100G-BDM2-* (Broadcom-based BDM2 platform)	C40G-BDM2M-* C100G-BDM2M-*	BDM2m Bi-Directional Module with Marvell Packet processor
All Custom Chassis Bundles with BDM1 or BDM2 line cards and/or IO1 and SW-IO1 Rear I/Os	BDM2m-based equivalent parts with IO2 as Rear I/O and SW-IO2-based redundancy kits.	Combination of BDM2m with existing IO2 and SW-IO2 as overall solution